

## Product / Process Change Notice

**Parts Affected:**

CPD69 wafer process: 1 Amp, glass passivated, standard recovery rectifiers.

**Extent of Change:**

Overall wafer thickness has been increased from 8.5 mils to 12.5 mils.

**Reason for Change:**

To reduce wafer breakage during manufacturing processes.

**Effect of Change:**

This change does not affect the electrical characteristics of any device.

**Qualification:**

Standard evaluation and qualifications completed resulting in no performance differences compared to current product.

**Effective Date of Change:**

Existing inventory will be shipped until depleted.

**Sample Availability:**

Please contact Salesperson or Manufacturer's Representative.

**Part #'s Affected:**

CMR1-02 Series	CPD69-CMR1-08M-WN
CMR1-02M Series	CPD69-1N3614-WN
CXR1-04	CPD69-1N4004-WN
CXR1-04C	CPD69-1N4006-CT
CZR1-04	CPD69-1N4007-CT
CZR1-04C	CPD69-1N4007-WN
CPD69-CMR1-02M-CT	CPD69-1N5614-CT
CPD69-CMR1-02M-WN	
CPD69-CMR1-02M-WR	
CPD69-CMR1-02M-WS	
CPD69-CMR1-06-WR	
CPD69-CMR1-06M-CT	
CPD69-CMR1-06M-WN	